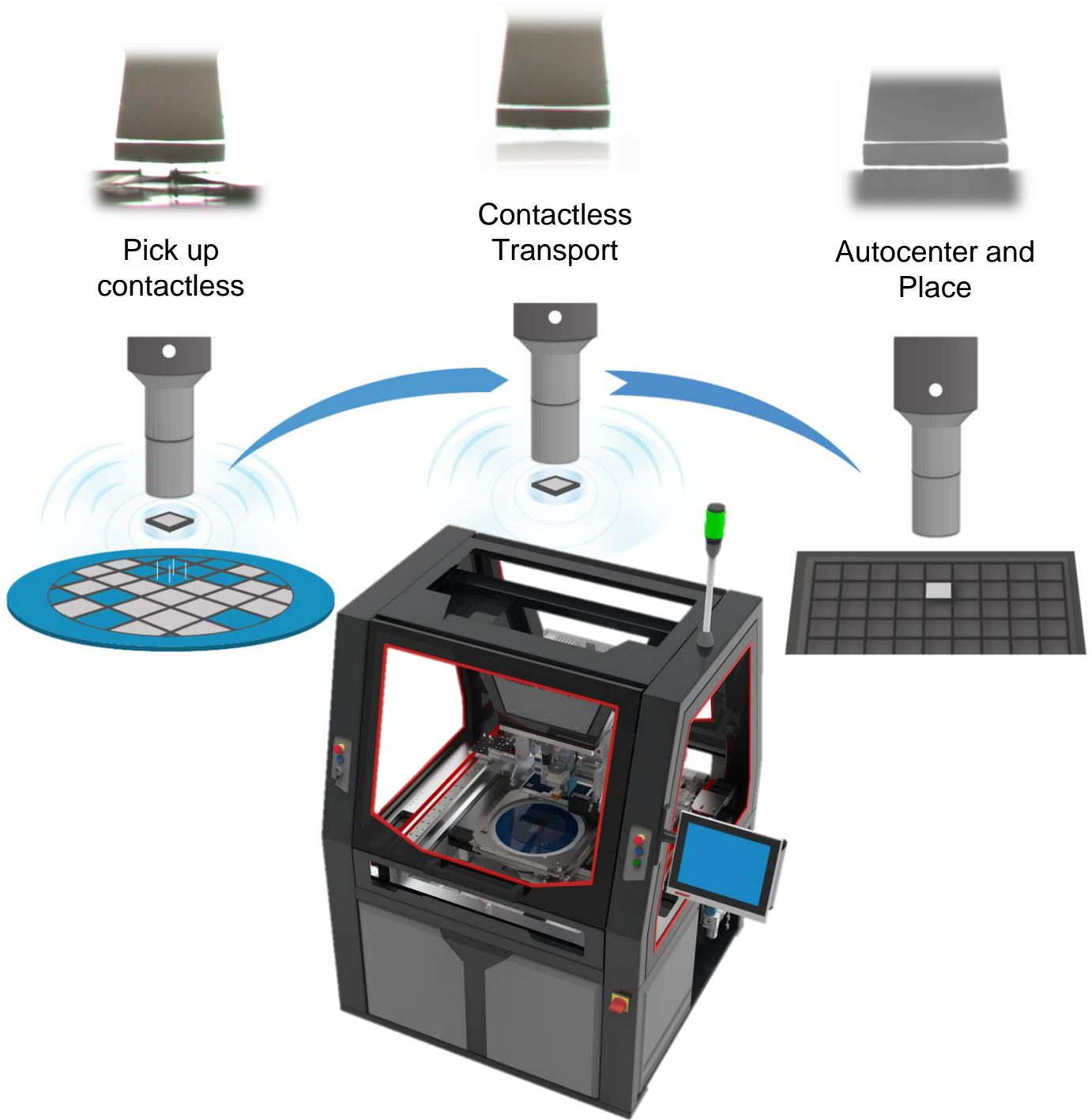




**TOUCHLESS+**  
**AUTOMATION**  
special micro-handling solution

*adtec*  
ASSEMBLY AUTOMATION TECHNOLOGY



# Levio

## Contactless pick & place machine

## Features & Options

### Base equipment

- Welded Frame/Base plate with safety protection and electronic cabinet
- Doors on both side
- Touch screen HMI
- Die ejection module with xy dynamic
- Contactless pick up head
- High precision motion control
- CE Marking
- UPH: 1000-1500 parts/hour

### Dimension and requirements

- Voltage 220-240 VAC / 12A Max
- Air pressure 6 Bars max
- Dimensions:
  - L = 1700mm
  - W = 1100mm
  - H = 1700mm
- Weight: 600 kg

### Components

- Any size from 0.5x0.5mm to 10x10mm
- Any material (GaAs, GaN, Glass, ...)
- Delicate surfaces and MEMS

### Features

- Inputs:
  - Wafer from 4" to 12"
  - Up to 6 waffle trays 4"
  - Up to 20 waffle trays 2"
  - 2 Jedec trays
- Outputs:
  - Up to 6 waffle/Gel Pak trays 4"
  - Up to 20 waffle/Gel Pak trays 2"
  - 2 Jedec trays
  - Tape & Reel module (optional)
- Flip module (optional)
- Vision inspection module (top/bottom)

## Contacts

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